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Product Change Notification

Product Group: TC/Sunday August 30, 2026/PCN-TC-014-2026-REV-0



Secure Lead frame supply chain for T51 Automotive products

For further information, please contact your regional Vishay office.

CONTACT INFORMATION

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Description of Change: Apply terminal 100% Sn plating before product assembly step instead of plating after the molding. No change in material content / product structure / FFF.

Reason for Change: Secure Lead frame supply chain for T51 Automotive products: introduce pre-plated Lead frames in order to simplify manufacturing process. Eliminate post mold plating by subcontractor and related logistics.

Expected Influence on Quality/Reliability/Performance: No.

Part Numbers/Series/Families Affected: T51*

Vishay Brand(S): Vishay Polytech

Time Schedule:

Start Shipment Date: Monday November 30, 2026

Sample Availability: Upon request.

Product Identification: N/A.

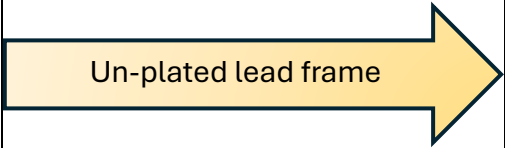
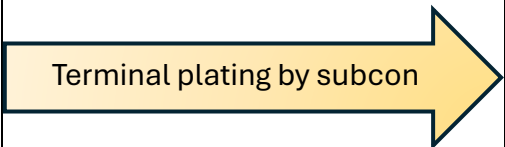
Qualification Data: Upon request.

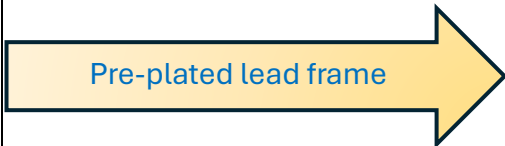
This PCN is considered approved, without further notification, unless we receive specific customer concerns before Wednesday September 30, 2026 or as specified by contract.

Issued By: Yuri Stangrit, yuri.stangrit@vishay.com

PCN-TC-014-2026-REV-0

Excerpt from T51 Polymer molded chip capacitors Process Flow Chart

	Step	Current process	Reference document
 Un-plated lead frame	18	Lead frame assembly	DTS-150
	19	Conductive paste cure	DTS-150
	20	Element coating	DTS-160
	21	Mold encapsulation	DTS-162
	22	Deflasher	DTS-164
 Terminal plating by subcon	23	Incoming inspection of Terminal plating (Outsource)	DTS-170
	24	Humidity conditioning after molding	DTS-171
	25	Marking	DTS-171

	Step	New process	Reference document
 Pre-plated lead frame	18	Lead frame assembly	DTS-150
	19	Conductive paste cure	DTS-150
	20	Element coating	DTS-160
	21	Mold encapsulation	DTS-162
	22	Deflasher	DTS-164
	23	Incoming inspection of Terminal plating (Outsource)	DTS-170
	24	Humidity conditioning after molding	DTS-171
	25	Marking	DTS-171

Vishay Material Code	Customer Material	Location
T51D106M035C0120	SPRT51D106M035C0120	Maisach Gernlinden
T51D107M016C0050	SPRT51D107M016C0050	Maisach Gernlinden
T51D227M010C0040	SPRT51D227M010C0040	Maisach Gernlinden
T51D336M020C0100	SPRT51D336M020C0100	Maisach Gernlinden
T51D337M004C0040	SPRT51D337M004C0040	Maisach Gernlinden
T51D337M6R3C0040	SPRT51D337M6R3C0040	Maisach Gernlinden
T51D476M025C0060	SPRT51D476M025C0060	Maisach Gernlinden
T51V337M2R5C0040	SPRT51V337M2R5C0040	Maisach Gernlinden
T51D476M025C0060	T51D476M025C0060	Singapore
T51D477M2R5C0006	T51D477M2R5C0006	Bucheon-si, Gyeonggi-do